



1/19

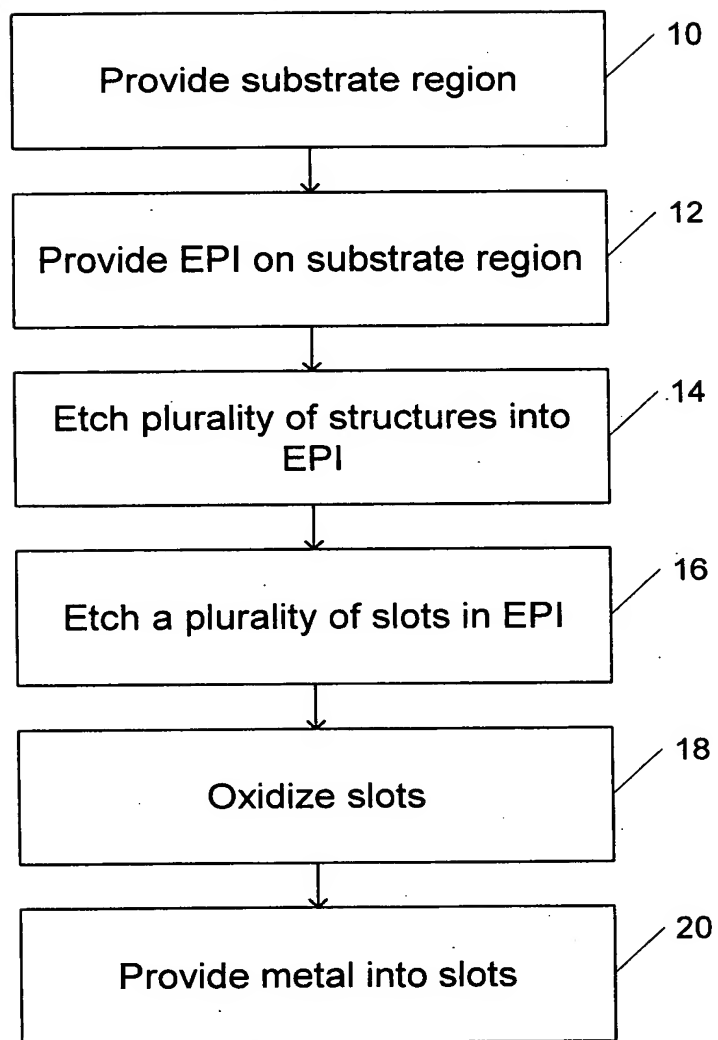


Fig. 1

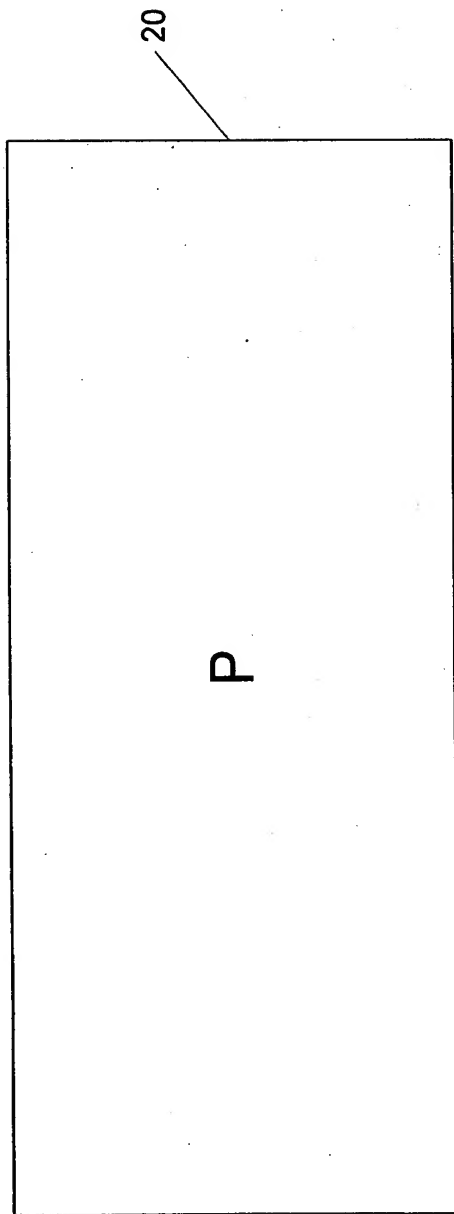


Fig. 2a

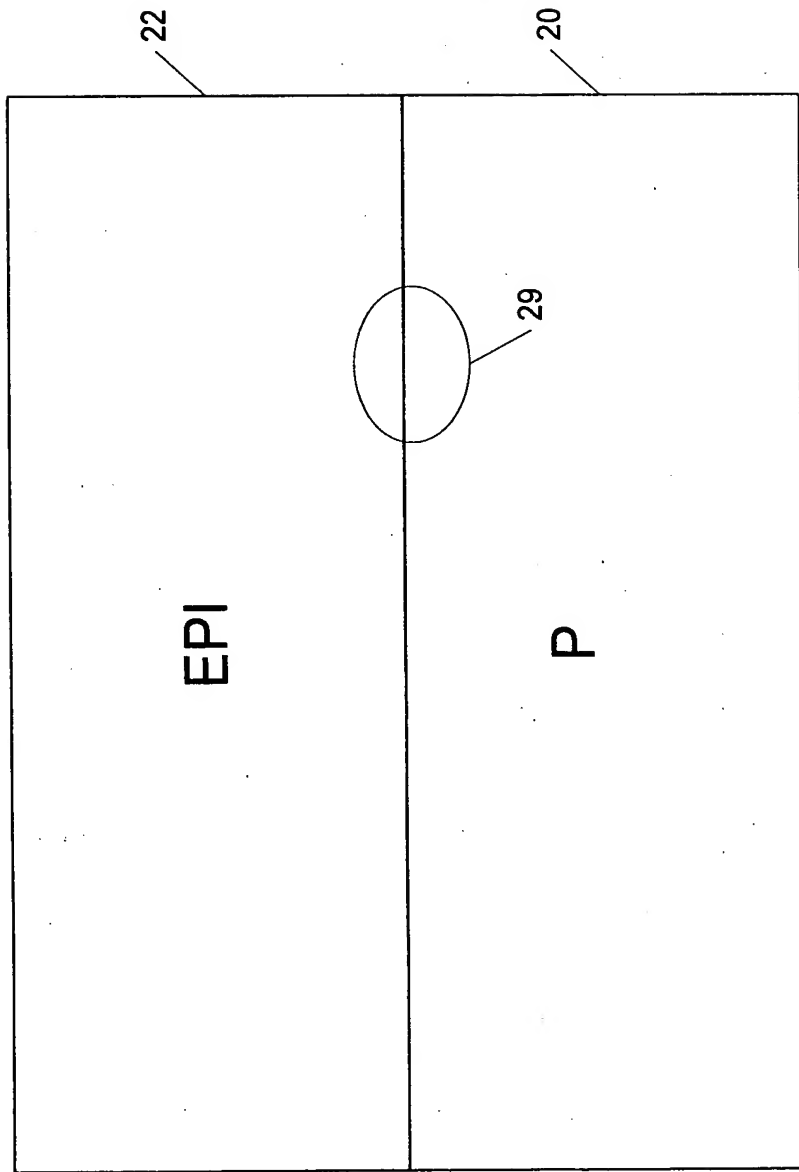


Fig. 2b

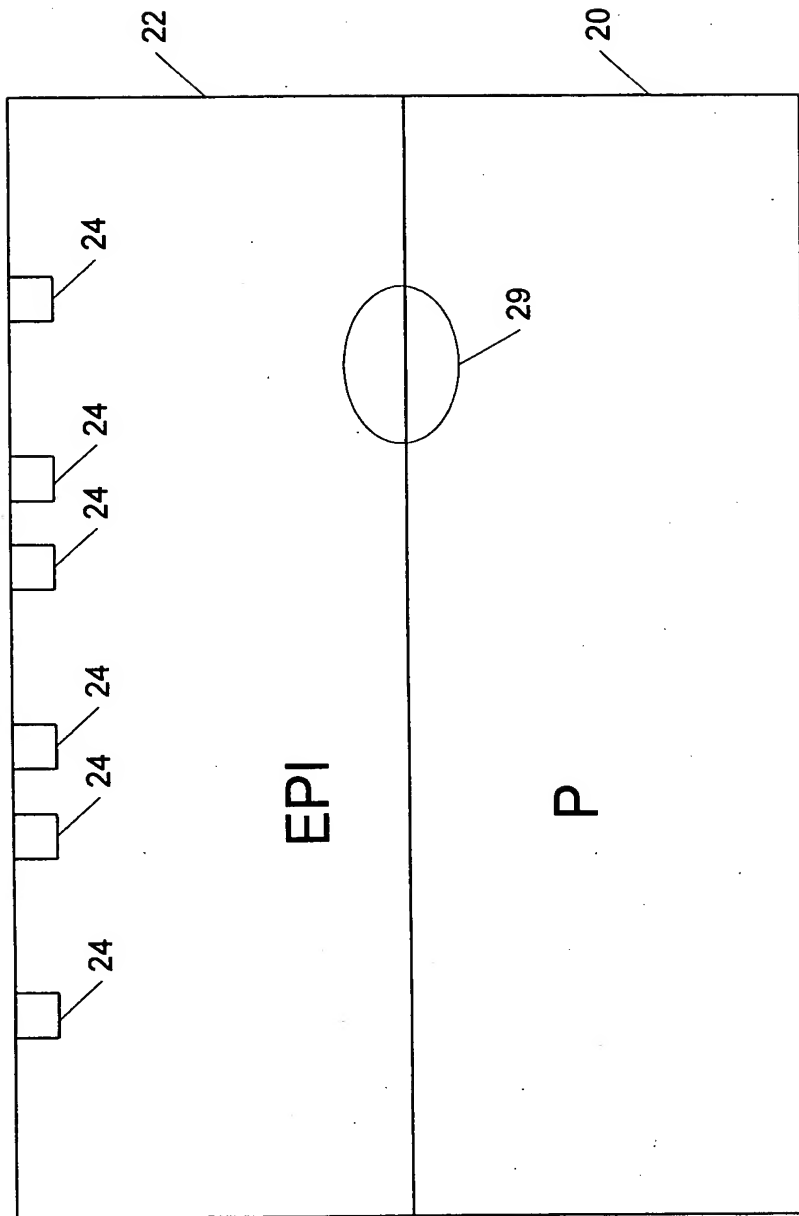


Fig. 2c

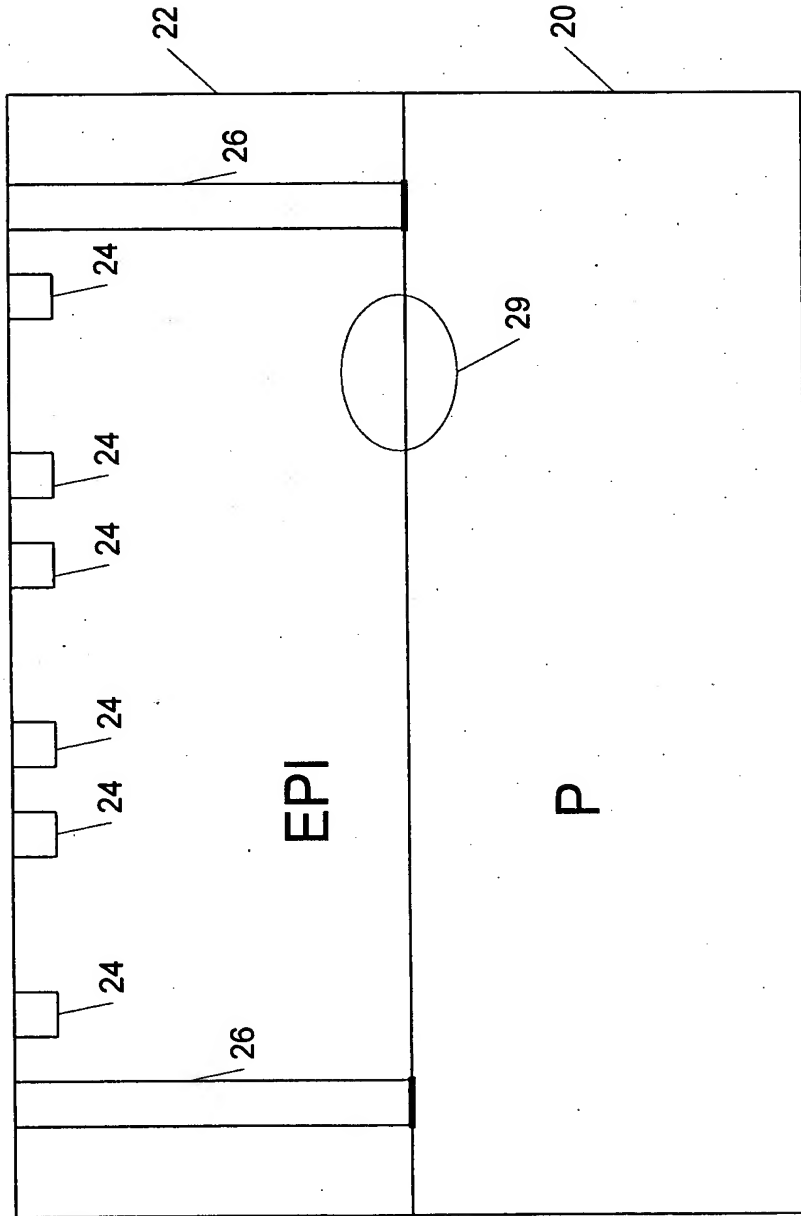


Fig. 2d

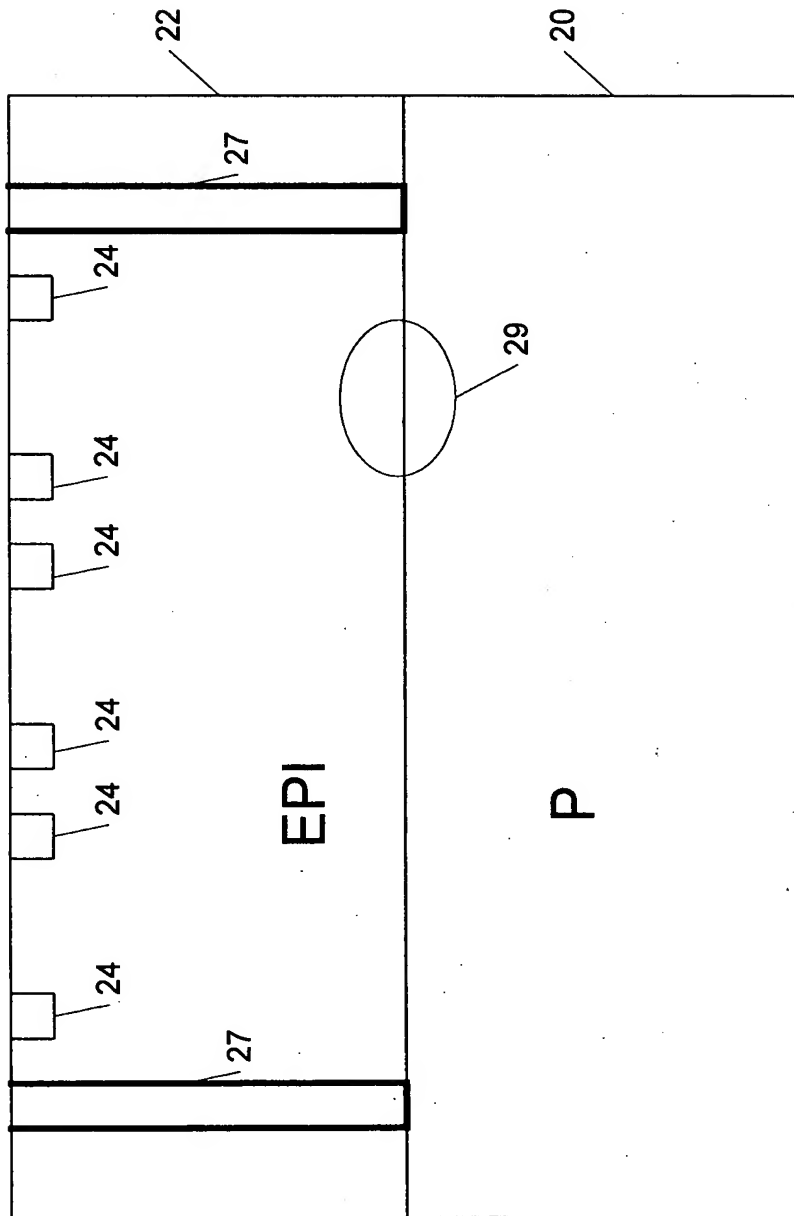


Fig. 2e

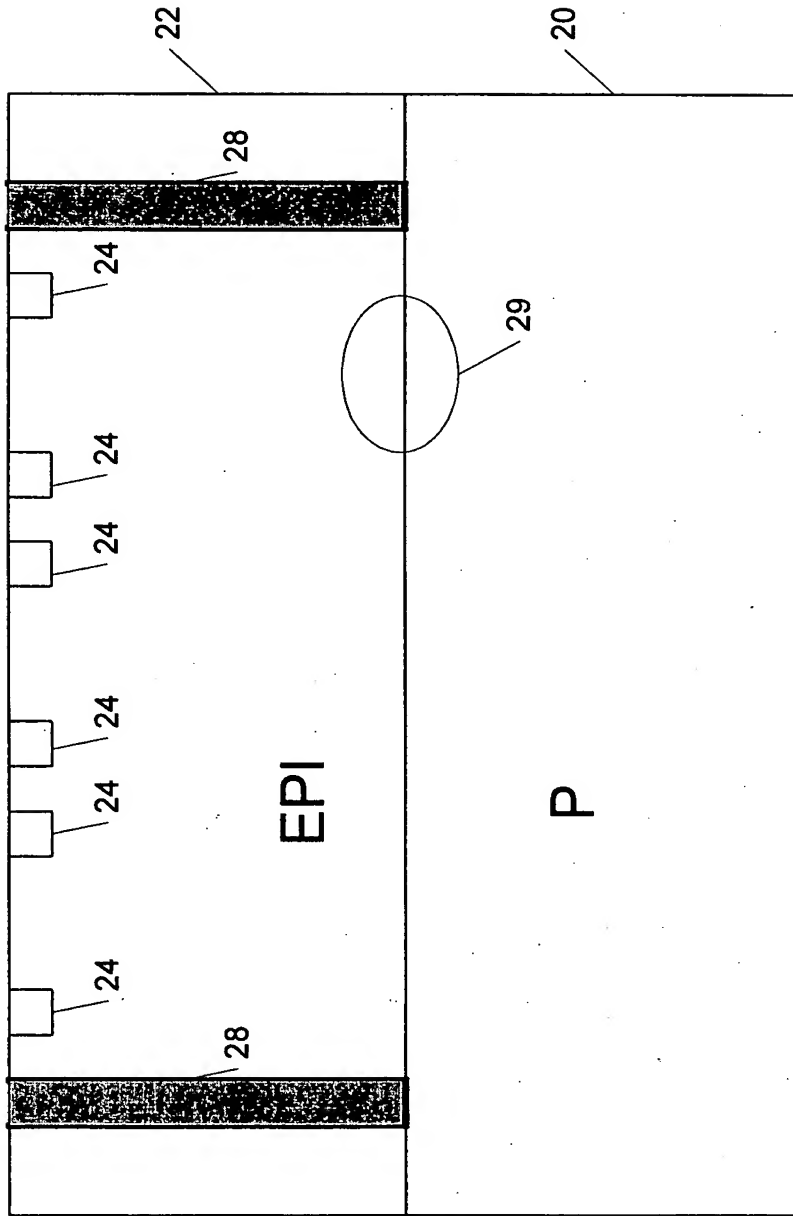


Fig. 2f

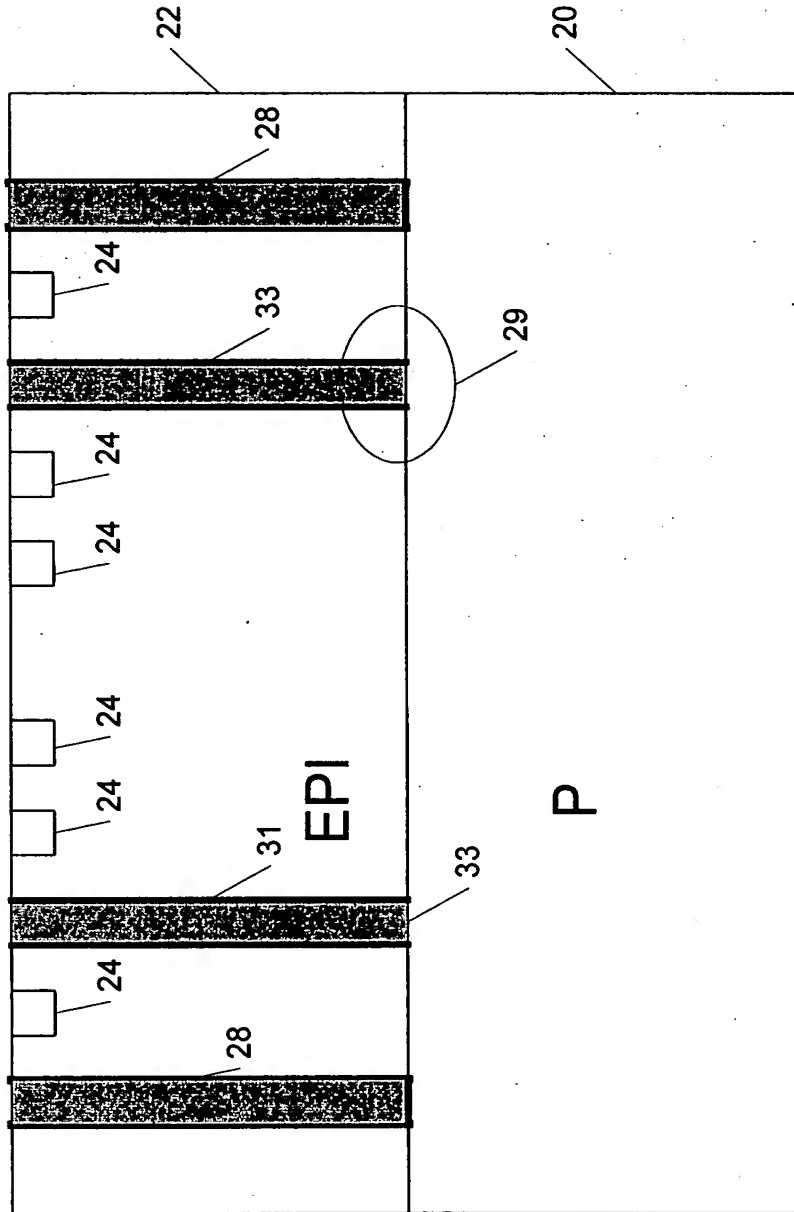


Fig. 2g

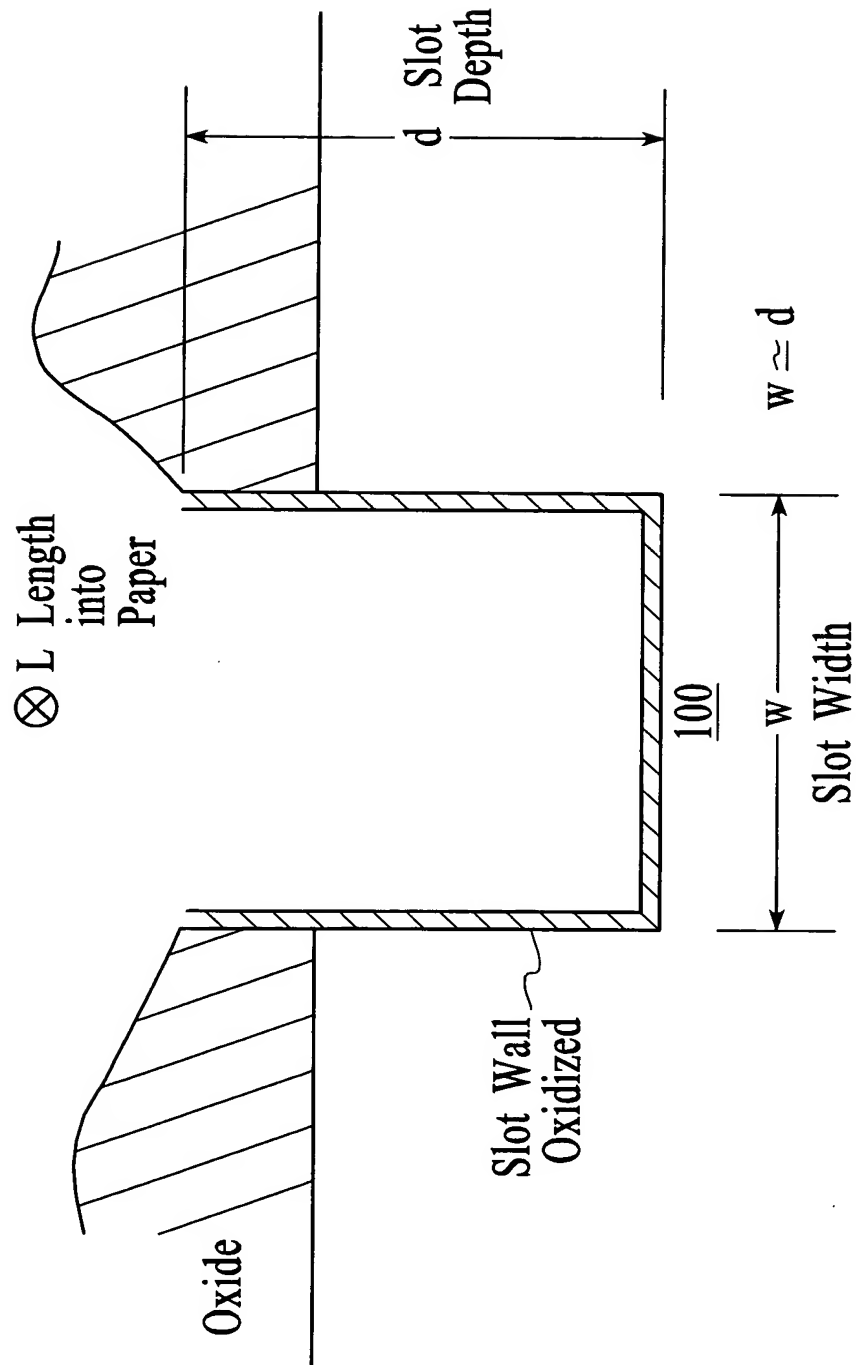


FIG. 3

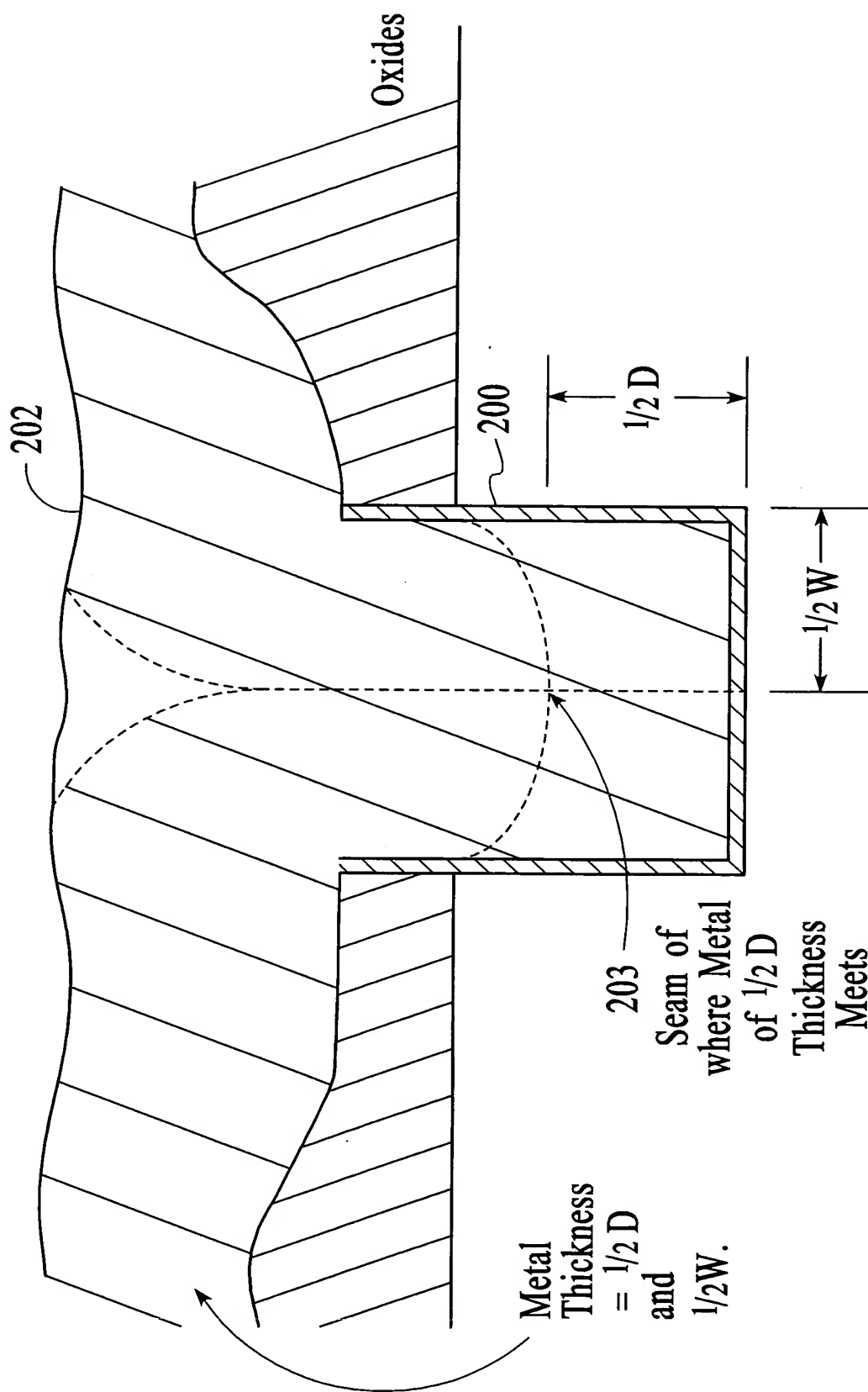


FIG. 4

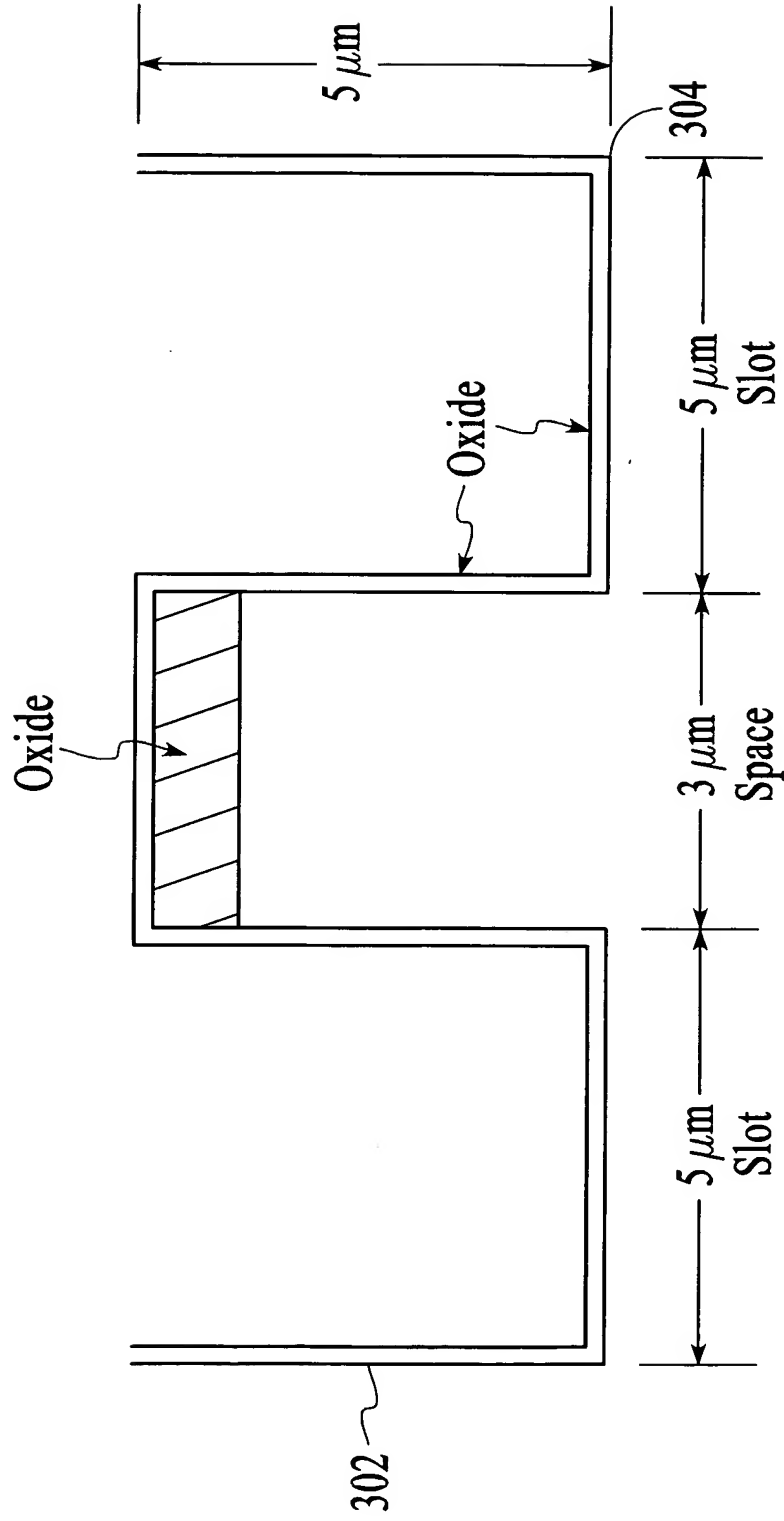
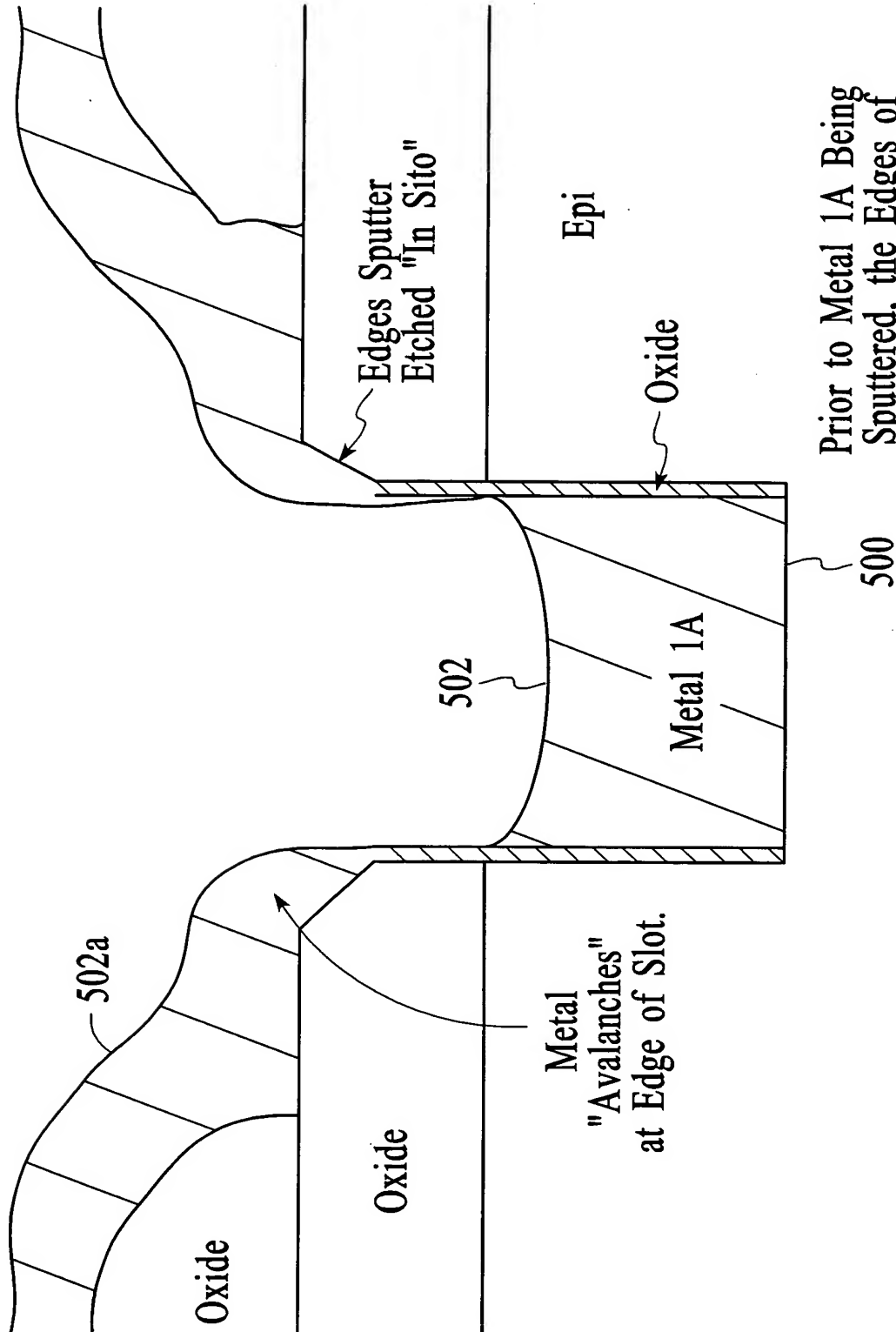


FIG. 4A



Prior to Metal 1A Being
Sputtered, the Edges of
the Oxides are Sputtered
Etched "In Situ" and
1A Deposited

FIG. 5

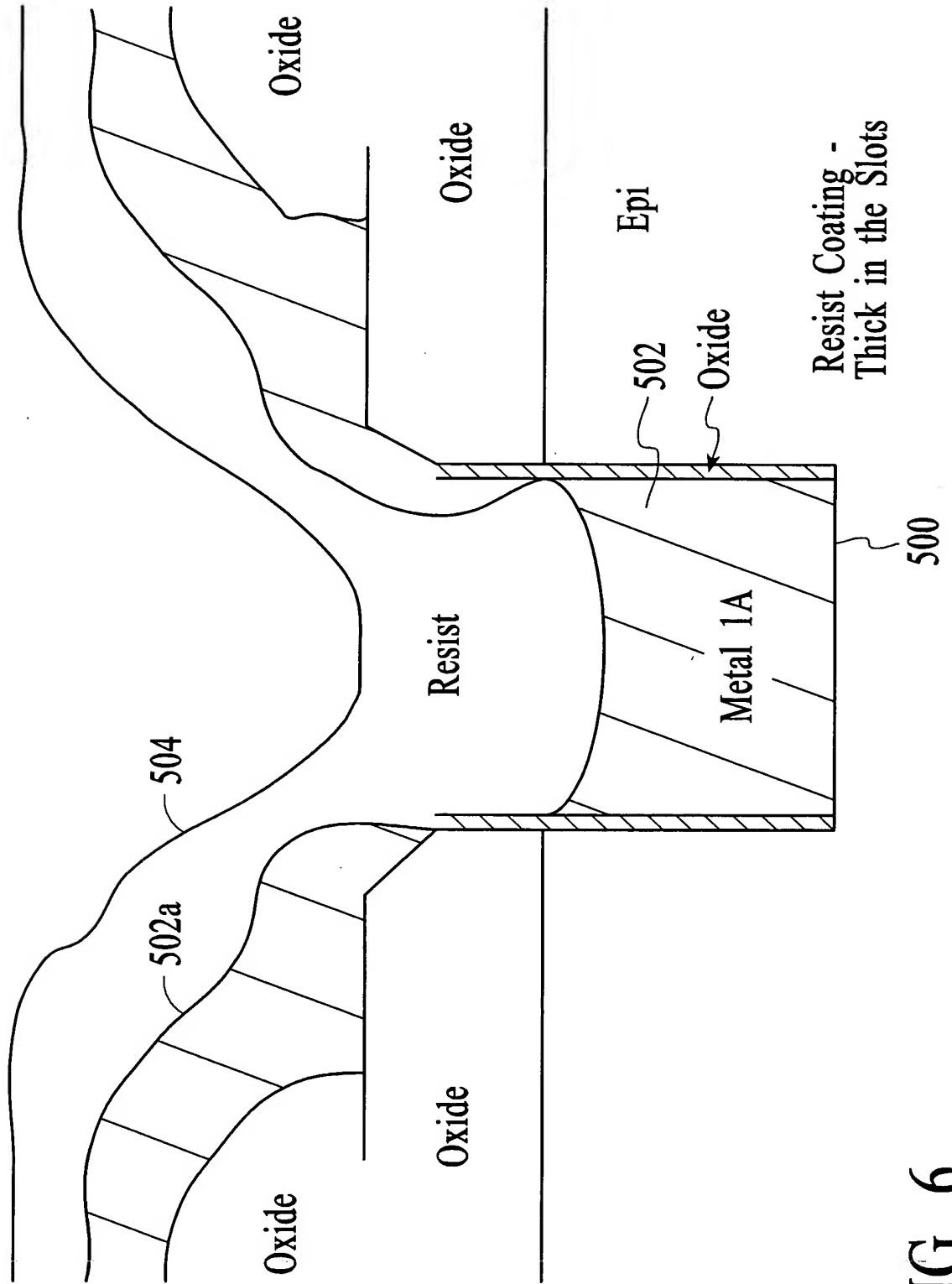
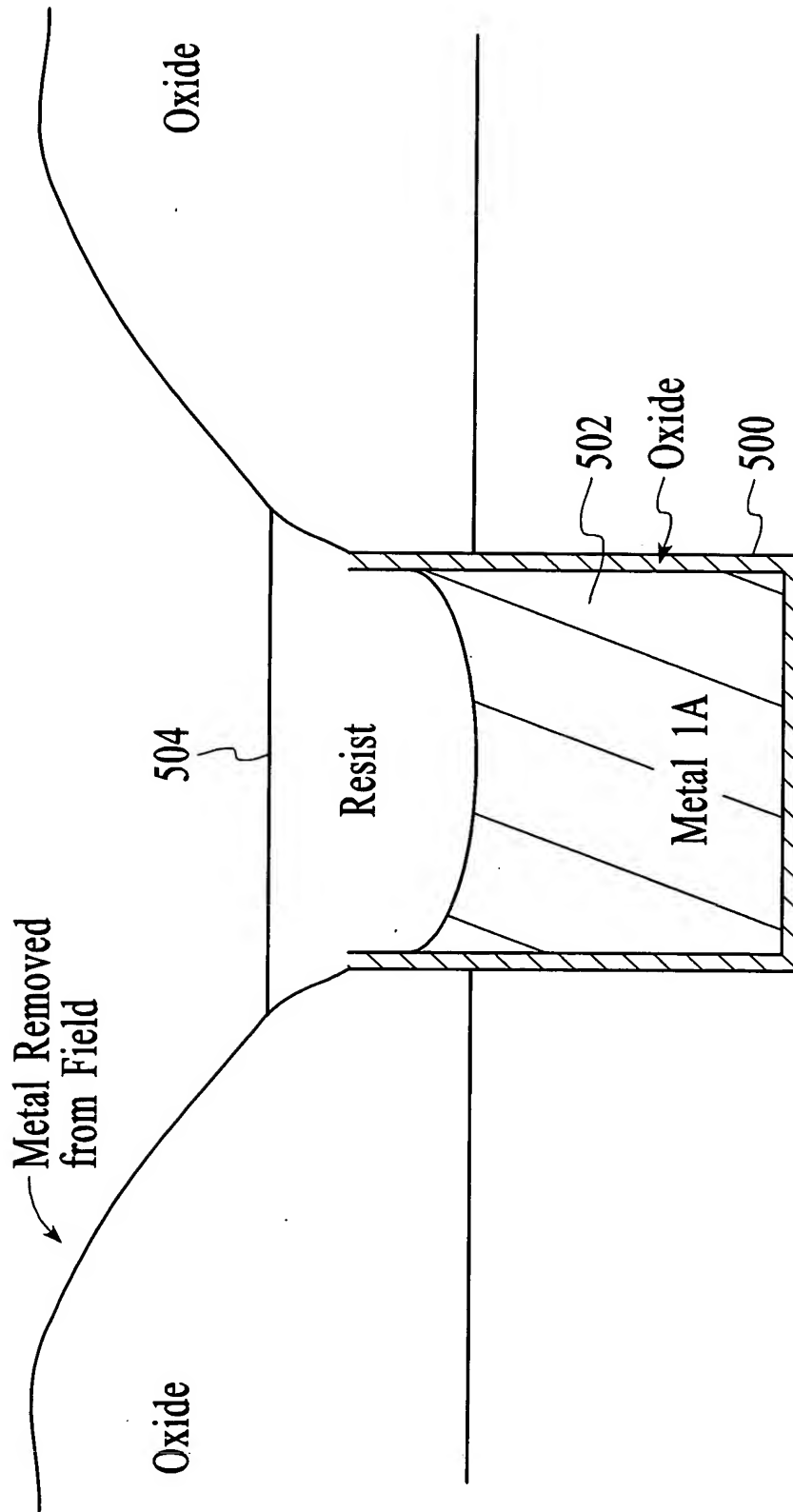
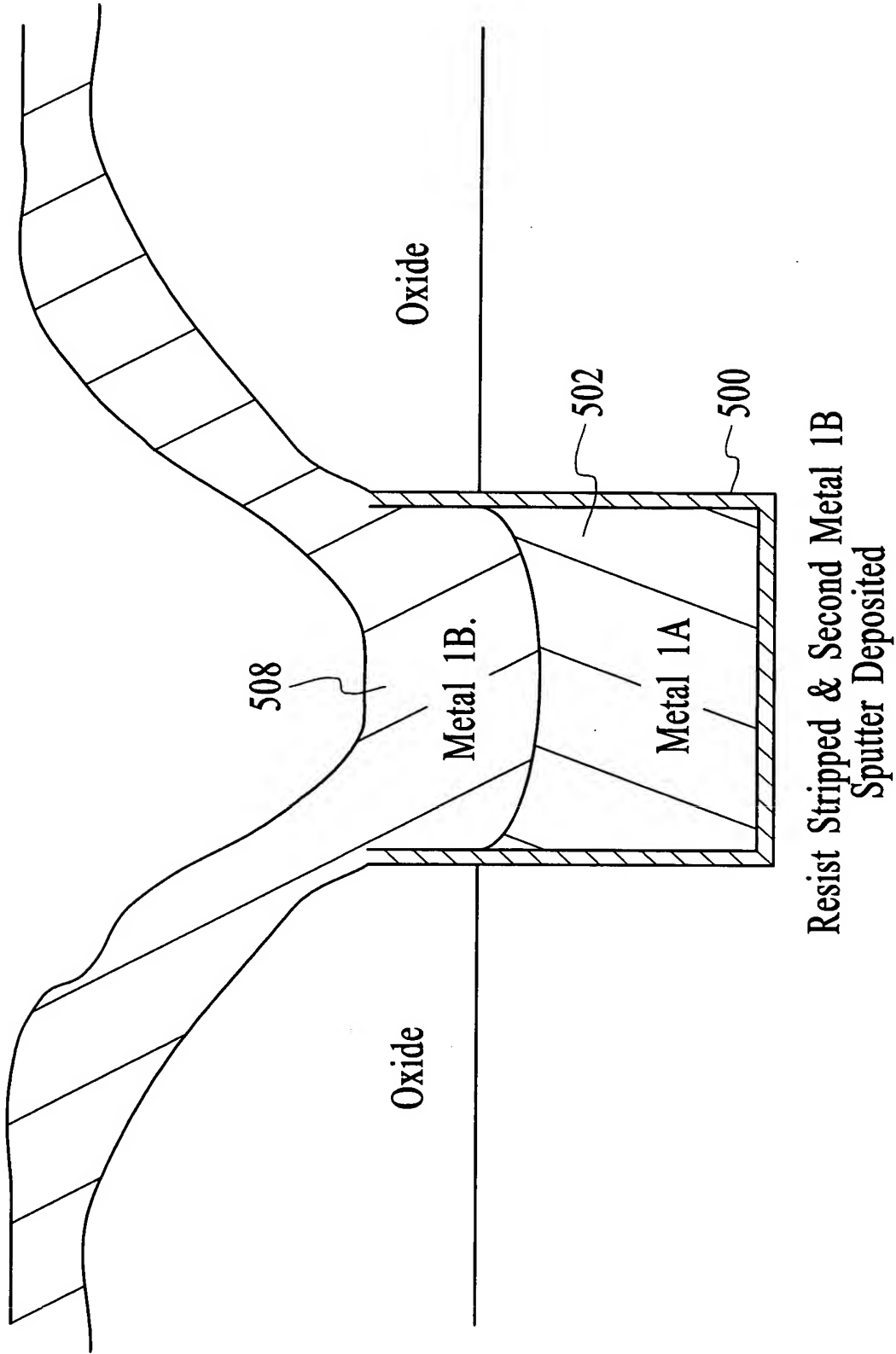


FIG. 6



Resist Planar Etched Leaving Resist
in Slots. Field Metal Etched Off.

FIG. 7



Resist Stripped & Second Metal 1B
Sputter Deposited

FIG. 8

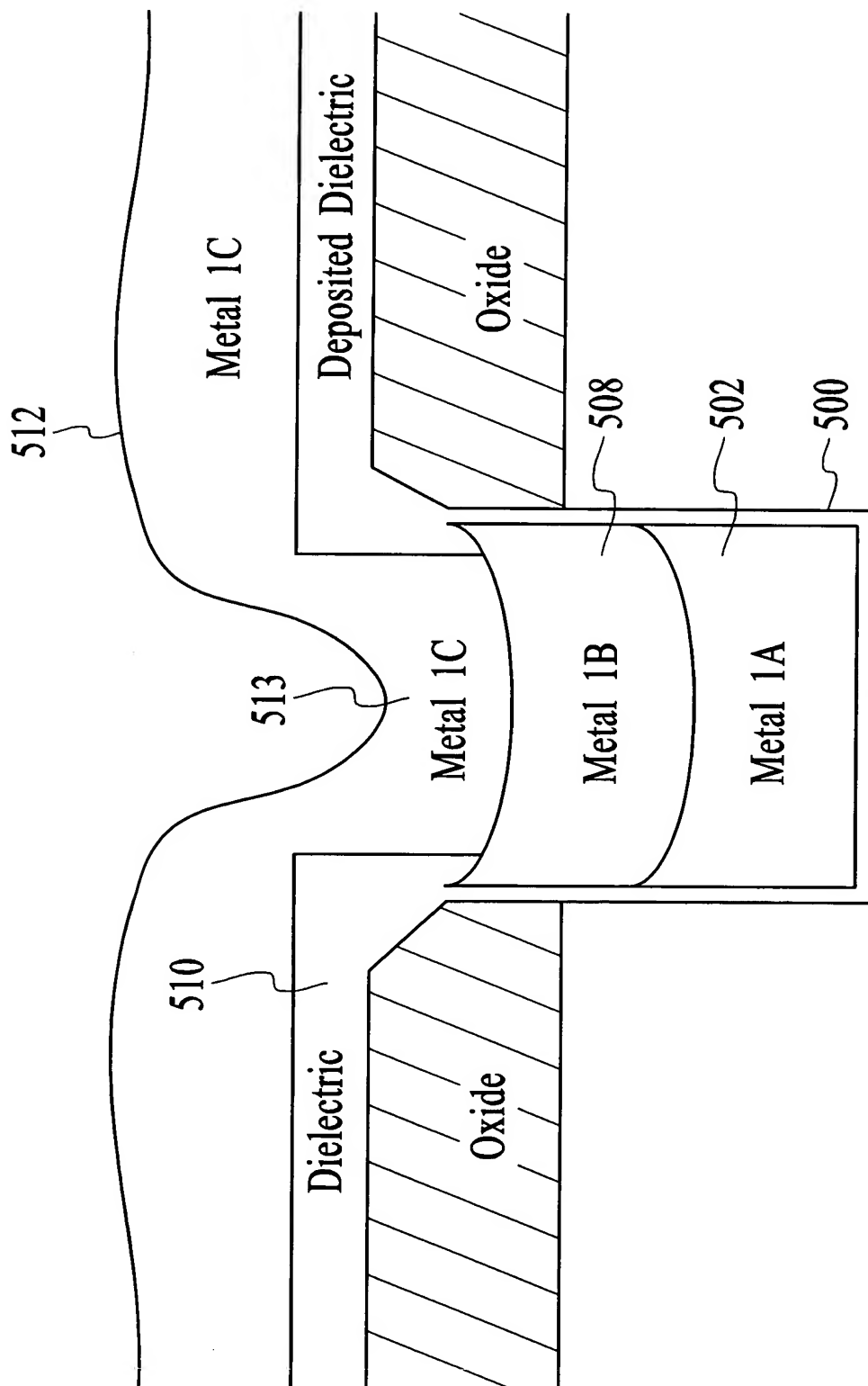


FIG. 9

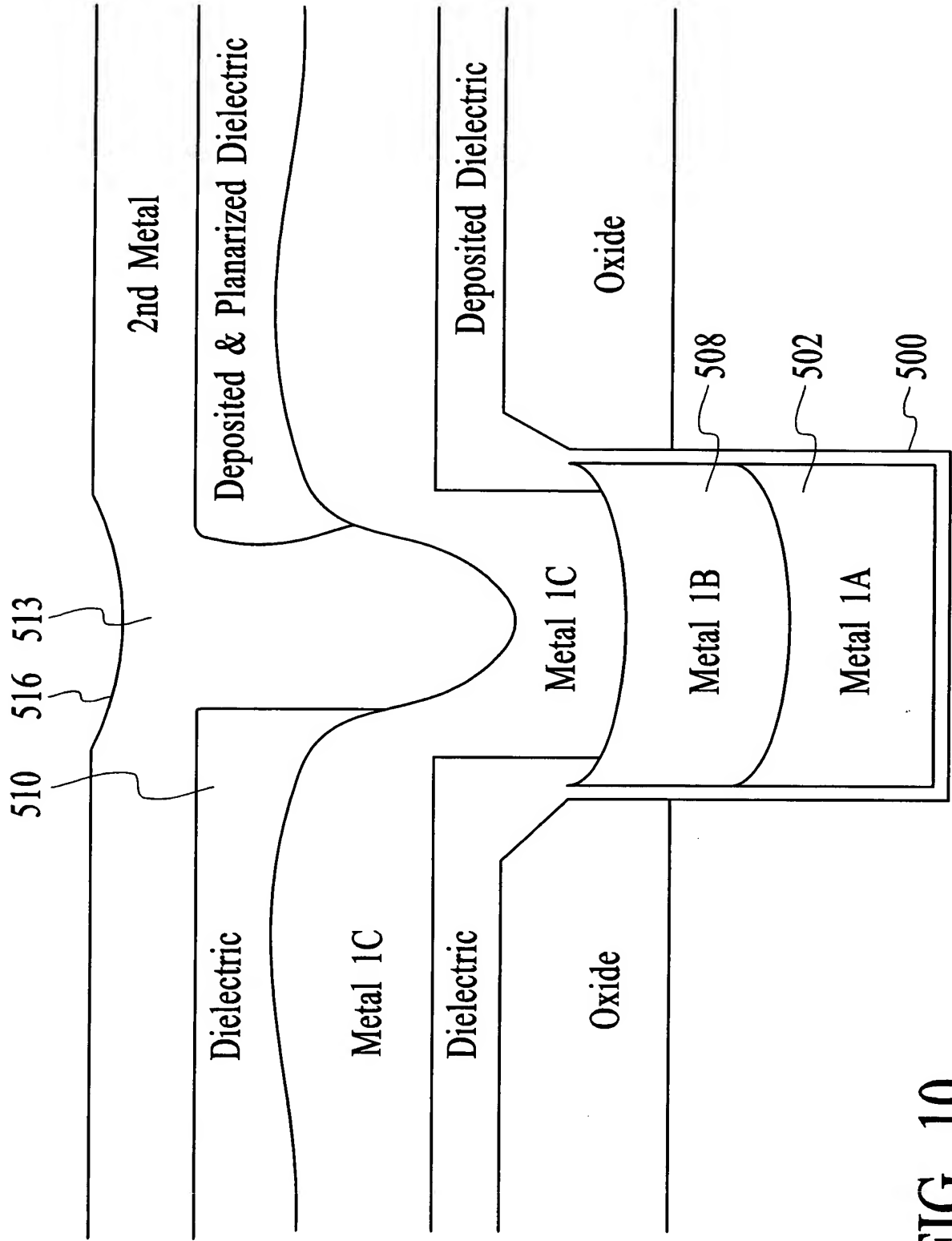
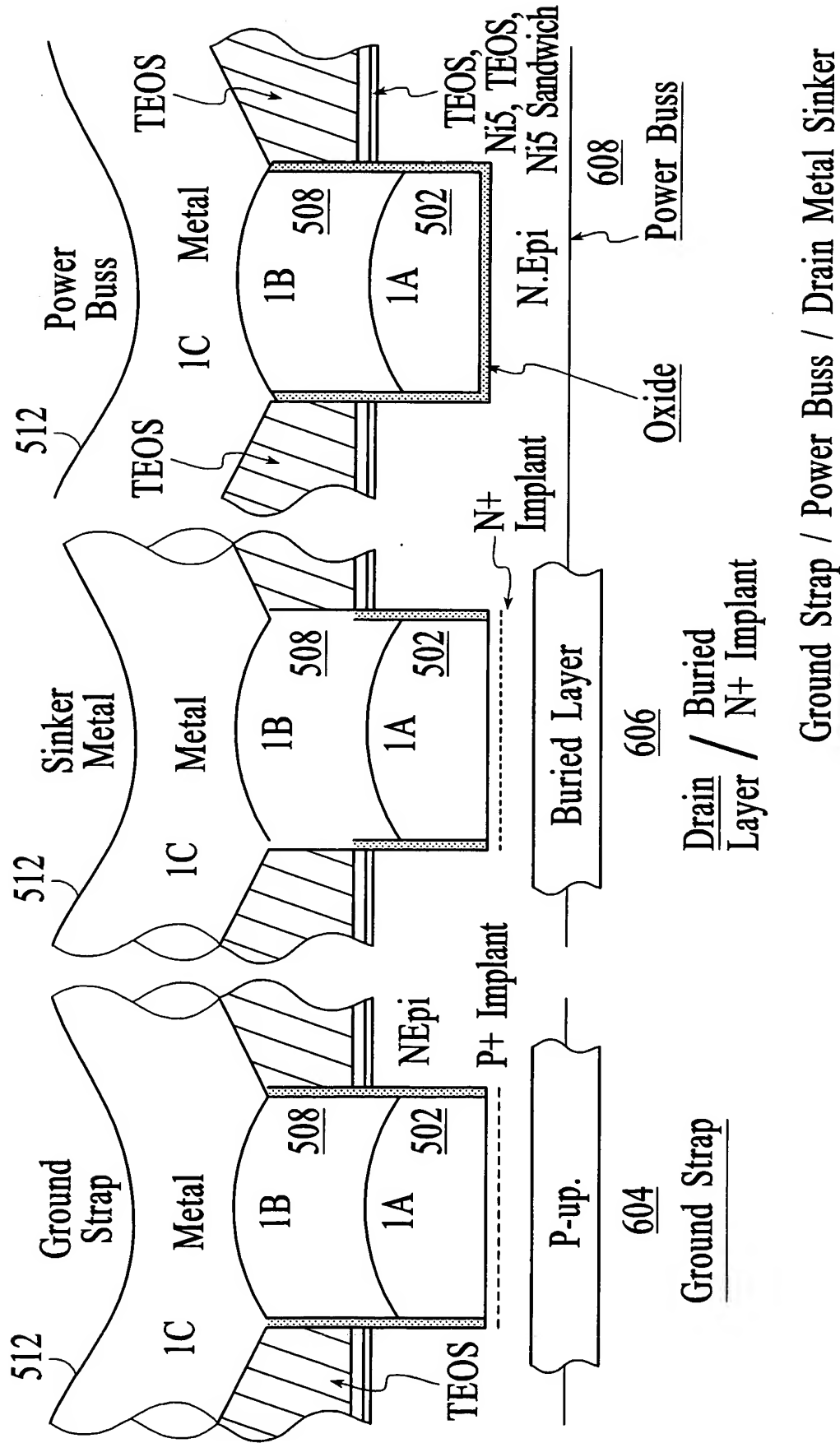


FIG. 10



Ground Strap / Power Buss / Drain Metal Sinker

Shown after layers of Dielectric followed by 90 OD Å TEOS - Polish - Slot Mask - Metal. Metal 1.5 - 2.0 μm deposited.

FIG. 11

Power Metal

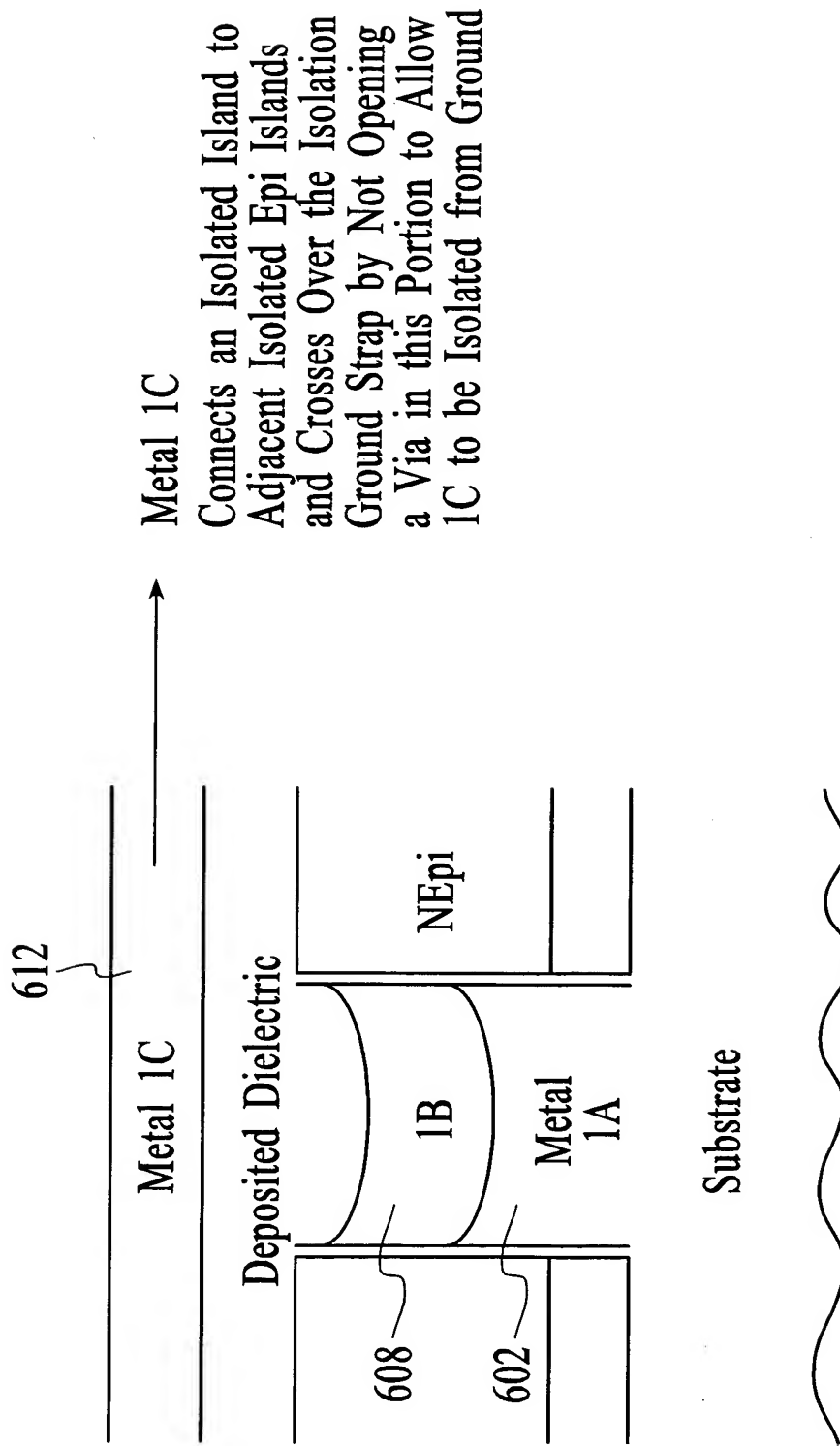


FIG. 12